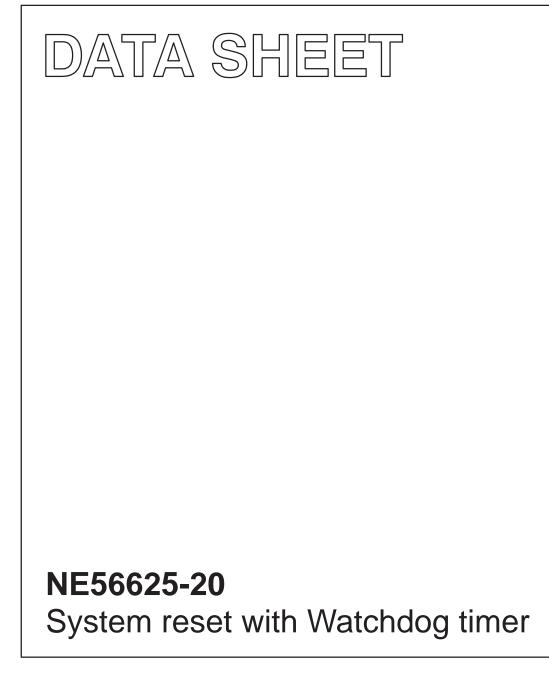
INTEGRATED CIRCUITS



Product data Supersedes data of 2002 Mar 25 2003 Oct 15



HILIP

NE56625-20

GENERAL DESCRIPTION

The NE56625-20 is comprised of a power-on reset, a Watchdog timer and low battery detection circuit. The NE56625 is designed to generate an Active-LOW reset signal for a variety of microprocessor and logic systems. Accurate reset signals are generated during momentary power interruptions or whenever power supply voltages sag to intolerable levels. The built-in Watchdog timer monitors the microprocessor and ensures it is operating properly. Any abnormal system operations due to microprocessor malfunctions are terminated by a system reset generated by the Watchdog. To accommodate a wide range of system requirements, the Watchdog Monitoring Time and power-on reset delay time are programmable from 10 ms to 10 sec.

The NE56625-20 is designed for low voltage battery powered applications with low battery detection threshold at 2.2 V. It is offered in the 8-lead small outline surface mount package (SOP005).

FEATURES

- Accurate threshold detection voltages:
 - Low battery: 2.2 V ±3%
 - Power-on reset: 2.0 V ±3%
- Low hysteresis voltage (both low battery check and power-on reset): 50 mV typ.
- Low supply current: 150 μA typ.
- Programmable power-on reset detection voltage
- Programmable power-on reset delay: 10 ms to 10 s
- Internal Watchdog timer programmable with external resistor and capacitor: 10 ms to 10 s
- Reset assertion with V_{CC} down to 0.8 V_{DC} (typical)
- Few external components required



APPLICATIONS

- Microcomputer systems and logic systems
- 2 V cordless phones
- Various portable, battery operated equipment

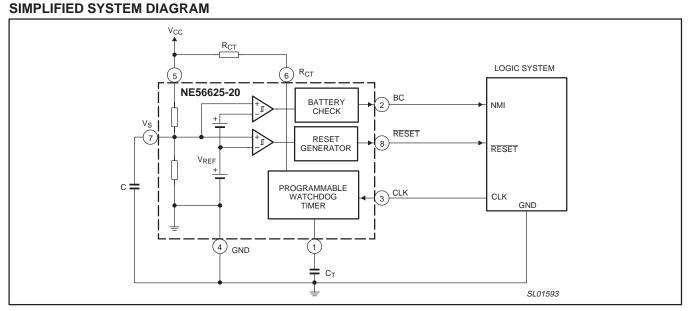


Figure 1. Simplified system diagram.

NE56625-20

ORDERING INFORMATION

TYPE NUMBER	PACKAGE					
NAME DESCRIPTION		DESCRIPTION	VERSION	RANGE		
NE56625-20D	SO8	lastic small outline package; 8 leads; body width 3.9 mm SOP005		–20 to +75 °C		

PIN CONFIGURATION

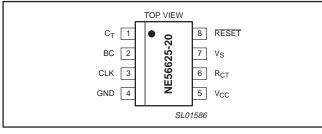


Figure 2. Pin configuration.

PIN DESCRIPTION

PIN	SYMBOL	DESCRIPTION
1	CT	t_{WDM} , t_{WDR} , t_{PR} adjustment pin. t_{WDM} , t_{WDR} , t_{PR} times are dependent on the value of external C _T capacitor used. See Figure 17 (Timing Diagram) for definition of t_{WDM} , t_{WDR} , t_{PR} times.
2	BC	Battery check Active-LOW output.
3	CLK	Clock input pin from logic system for Watchdog timer.
4	GND	Circuit ground.
5	V _{CC}	Positive supply voltage.
6	R _{CT}	Watchdog timer control pin. The Watchdog timer is enabled when this pin is pulled-up to V _{CC} with a resistor, and disabled when this pin is connected to ground.
7	V _S	Detection threshold adjustment pin. The detection threshold can be decreased by connecting this pin to V_{CC} with a pull-up resistor. The detection threshold can be increased by connecting this pin to ground with a pull-down resistor.
8	RESET	Reset Active-LOW output.

MAXIMUM RATINGS

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V _{CC}	Power supply voltage	-0.3	7	V
V _{VS}	V _S pin voltage	-0.3	7	V
V _{CLK}	CLK pin voltage	-0.3	7	V
V _{OH}	RESET and BC pin voltage	-0.3	7	V
T _{oper}	Operating temperature	-20	+75	°C
T _{stg}	Storage temperature	-40	+125	°C
Р	Power dissipation	-	300	mW

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	RATING	UNIT
V _{CC}	Power supply voltage	1.9 to 6.5	V
I _{OLR}	RESET sink current	0 to 500	μA
I _{OLC}	BC sink current	0 to 5.0	mA
V _{CKH}	HIGH-level clock input voltage	< 1.0	V
V _{CKL}	LOW-level clock input voltage	< 0.2	V
t _{WD}	Clock monitoring time	1 to 10,000	ms
t _{r(CLK)} , t _{f(CLK)}	Clock rise and fall times	< 100	μs
t _{r(VCC)}	Power supply voltage rise time	< 100	μs
t _{f(VCC)}	Power supply voltage fall time	< 50	μs
T _{amb}	Operating ambient temperature	-20 to +70	°C
C _T	TC capacitance	0.0022 to 2.2	μF

DC ELECTRICAL CHARACTERISTICS

 T_{amb} = 25 °C, V_{CC} = 2.6 V, unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CC}	Supply current during Watchdog timer operation	no load	_	0.7	1.0	mA
V _{SLR}	RESET detection threshold	V_{CC} = falling; R_{CT} : GND; V_{S} = open	1.94	2.0	2.06	V
$\Delta V_{SR} / \Delta T_{amb}$	Temperature coefficient of reset detection voltage	$-20~^\circ C \leq T_{amb} \leq 70~^\circ C$	_	±0.01	±0.05	%/°C
V _{hysR}	RESET threshold hysteresis	V_{CC} = falling; R_{CT} : GND; V_{S} = open	25	50	100	mV
V _{SLB}	Battery detection voltage	V_{CC} = falling; R_{LB} = 10 k Ω	2.13	2.20	2.27	V
$\Delta V_{SB} / \Delta T_{amb}$	Temperature coefficient of battery detection voltage		-	±0.01	±0.05	%/°C
V _{hysB}	Battery hysteresis voltage	V_{CC} = falling; R_{LB} = 10 k Ω	25	50	100	mV
ΔV_{SL}	Detection voltage difference	$\Delta V_{SL} = V_{SLB} - V_{SLR}$	175	200	225	mV
V _{TH}	CLK input threshold		0.8	1.2	2.0	V
I _{IH}	HIGH-level CLK input current	V _{CLK} = 2.6 V	-	0	1	μΑ
IIL	LOW-level CLK input current	V _{CLK} = 0 V	-15	-6	-2	μΑ
V _{OHR}	HIGH-level output voltage, RESET	$I_{RESET} = -1.0 \ \mu A; V_S = open$	2.0	2.2	-	V
V _{OHB}	HIGH-level output voltage, BC	R _{LB} = 10 kΩ	2.0	2.2	-	V
V _{OLR}	LOW-level output voltage, RESET	$I_{\overline{\text{RESET}}} = 500 \ \mu\text{A}; \ V_{CC} = 1.8 \ \text{V}$	-	0.3	0.5	V
V _{OLB}	LOW-level output voltage, BC	$I_{BC} = 5 \text{ mA}; V_{CC} = 1.8 \text{ V}$	-	0.3	0.5	V
I _{OLR}	RESET output sink current	$V_{\overline{RESET}} = 0.5 \text{ V}; V_{CC} = 1.8 \text{ V}$	500	700	-	μΑ
I _{OLB}	Battery Check output sink current	V_{BC} = 0.5 V; V_{CC} = 1.8 V	5	7	-	mA
I _{OHR}	RESET output source current	V _{RESET} = 2.0 V	2	4	-	μΑ
I _{CT1}	C _T charge current	V _{CT} = 0.5 V; during Watchdog operation	-0.3	-0.15	-0.075	μA
I _{CT2}		V _{CT} = 0.5 V; during power-on reset operation	-0.3	-0.15	-0.075	μA
V _{CCL}	Supply voltage to assert reset operation	$V_{RESET} = 0.4 \text{ V}; I_{RESET} = 0.05 \text{ mA}$	_	0.8	1.0	V

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AC ELECTRICAL CHARACTERISTICS

Characteristics measured with V_{CC} = 2.6 V, and T_{amb} = 25 °C, unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
t _{P1}	Minimum power supply pulse width for detection	4.0 V \leq negative-going V _{CC} pulse \leq 5.0 V	8.0	_	-	μs
t _{CLKW}	Clock input pulse width		3.0	-	-	μs
t _{CLK}	Clock input cycle		20	-	-	μs
t _{WDM}	Watchdog monitoring time (Notes 1, 6)	$C_T = 0.022 \ \mu\text{F}; \ R_{CT} = \text{open}$	50	100	150	ms
t _{WDR}	Watchdog reset time (Notes 2, 6)	$C_T = 0.022 \ \mu F$	1.0	2.0	3.0	ms
t _{PR}	Power-on reset delay time (Notes 3, 6)	V_{CC} = rising from 0 V; C_T = 0.022 μ F	50	100	150	ms
t _{PDR}	RESET propagation delay time (Note 4)	V_{CC} = falling; R_{LR} = 100 k Ω ; C_{LR} = 15 pF	-	10	-	μs
t _{PDB}	Battery Check propagation delay time (Note 4)	V_{CC} = falling; R_{LB} = 10 k Ω ; C_{LB} = 15 pF	-	10	-	μs
t _{RR}	RESET rise time (Note 5)	ESET rise time (Note 5) $R_{LR} = 100 \text{ k}\Omega; C_{LR} = 15 \text{ pF}$		10	-	μs
t _{FR}	RESET fall time (Note 5)	R _{LR} = 100 kΩ; C _{LR} = 15 pF	-	2	-	μs
t _{RB}	Battery Check rise time (Note 5)	$R_{LB} = 10 \text{ k}\Omega; C_{LB} = 15 \text{ pF}$	-	10	-	μs
t _{FB}	Battery Check fall time (Note 5)	R _{LB} = 10 kΩ; C _{LB} = 15 pF	-	2	-	μs

NOTES:

1. 'Watchdog monitoring time' (t_{WDM}) is the duration from the last pulse (negative-going edge) of the timer clear clock pulse until reset output pulse occurs (see Figure 17). A reset signal is output if a clock pulse is not input during this time. 'Watchdog reset time' (t_{WDR}) is the reset pulse width. Do not confuse this with the power-on reset delay time (t_{PR}).

2

The power-on reset delay or hold time is the duration measured from the time V_{CC} exceeds the upper detection threshold (V_{SHR}) and 3.

power-on reset release is experienced (RESET output HIGH). 'Reset response time' is the duration from when the supply voltage sags below the lower detection threshold (V_{SL}) and reset occurs (RESET 4. output LOW).

5. Reset rise and fall times and Battery Check rise and fall times are measured at 10% and 90% output levels.

6. Watchdog monitoring time (t_{WDM}), Watchdog reset time (t_{WDR}), and power-on reset delay time (t_{PR}) during power-on can be modified by varying the C_T capacitance. The times can be approximated by applying the following formula. The recommended range for C_T is 0.0022 µF to 2.2 μF.

Formula 1. Calculation for approximate t_{PR}, t_{WDM}, and t_{WDR} values:

 t_{PR} (ms) $\approx 4500 \times C_T$ (μ F) t_{WDM} (ms) $\approx 4500 \times C_T$ (μ F) t_{WDR} (ms) $\approx 90 \times C_T$ (μ F)

Example: When $C_T = 0.022 \ \mu F$ and $R_{CT} =$ open:

t_{PR} ≈ 100 ms

 $t_{WDM}\approx 100\ ms$ $t_{WDR} \approx 2.0 \text{ ms}$

NE56625-20

TYPICAL PERFORMANCE CURVES

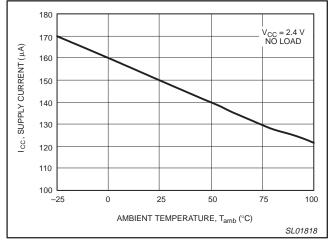


Figure 3. Supply current versus ambient temperature.

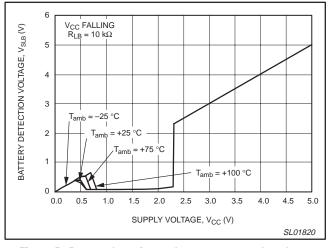


Figure 5. Battery detection votlage versus supply voltage.

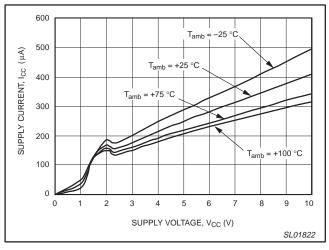


Figure 7. Supply current versus supply voltage.

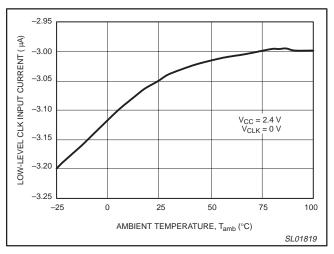


Figure 4. LOW-level CLK input current versus ambient temperature.

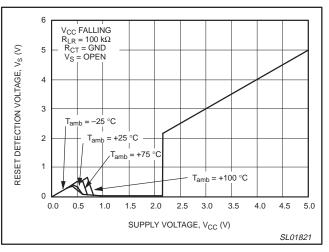


Figure 6. RESET detection voltage versus supply voltage.

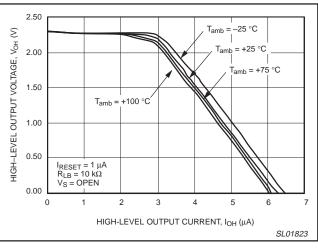


Figure 8. HIGH-level output voltage versus HIGH-level output current

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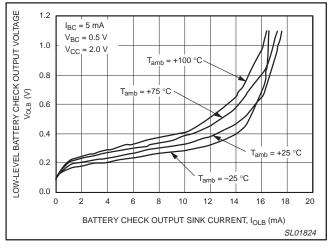


Figure 9. Battery check LOW-level output voltage versus battery check output sink current

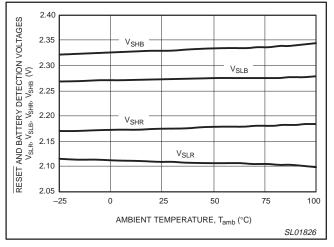


Figure 11. RESET and battery detection voltages versus temperature.

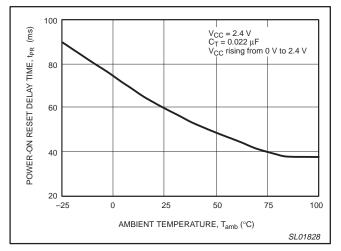


Figure 13. Power-on reset delay time versus temperature.

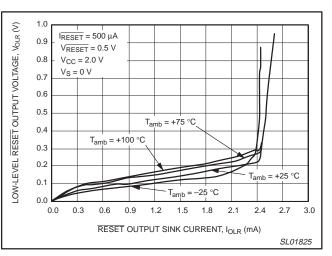


Figure 10. LOW-level RESET output voltage versus RESET output sink current.

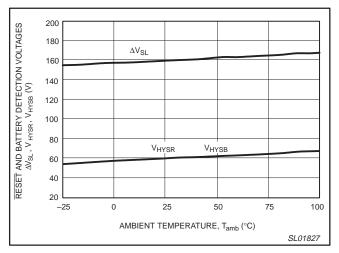


Figure 12. RESET and battery hysteresis voltages versus temperature.

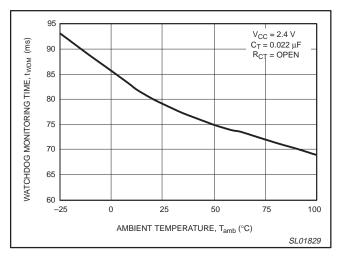


Figure 14. Watchdog monitoring time versus temperature.

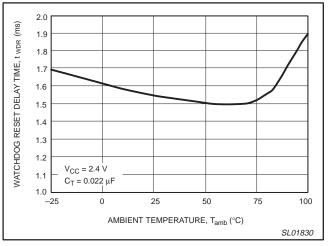


Figure 15. Watchdog reset delay time versus temperature.

NE56625-20

TECHNICAL DESCRIPTION

The NE56625-20 combines a Watchdog timer, a Battery Check and an Undervoltage Reset functions in a single SO8 surface mount package. This provides a space-saving solution for maintaining proper operation of typical 2.0 volt cordless telephone and other low voltage portable, handheld communication and industrial equipment.

While the Watchdog monitors the microprocessor operation, the Battery Check and Undervoltage Reset monitor the supply voltage to the microprocessor. If the microprocessor clock signal ceases or becomes erratic, the NE56625-20 outputs a reset signal to the microprocessor. If the microprocessor supply voltage sags to 2.0 volts or less, the NE56625-20 outputs a reset signal for the duration of the supply voltage deficiency. The Undervoltage Reset signal allows the microprocessor to shut down in an orderly manner to avoid system corruption. In addition to a RESET output, the NE56625-20 has a Battery Check output for system use. If the supply voltage sags below 2.2 volts or less, the Battery Check output goes LOW and remains LOW until the supply voltage recovers. Both the undervoltage detection threshold and battery check detection threshold incorporate hysteresis to prevent generating erratic resets.

The Watchdog timer requires a pulse input. Normally this signal comes from the system microprocessor's clock. For operation, pin 6 is not connected (open) or an external resistor (R_{CT}) of 1 M Ω or greater is connected from Pin 6 to V_{CC} and an external capacitor (C_T) is placed from Pin 1 to ground. The recommended range for C_T capacitor is 2.2 nF to 2.2 μ F. The external R_{CT} resistor and C_T capacitor establish the required minimum frequency of Watchdog input signal for the device to **not** output a reset signal. The R_{CT} resistor establishes, in part, the rate of charge of the C_T capacitor. In the absence of a Watchdog input pulse, the C_T capacitor charges to the 0.2 volt threshold of the internal comparator, causing a reset signal to be output. If microprocessor clock signals are received within the required interval, no Watchdog reset signal will be output. The Watchdog function can be disabled by grounding Pin 6 without affecting the undervoltage detection function.

Although the temperature coefficient of detection threshold is specified over a temperature of -20 °C to +70 °C, the device will support operation in excess of this temperature range. See the supporting curves for performance over the full temperature range of -25 °C to +100 °C. Some degradation in performance will be experienced at the temperature extremes and the system designer should take this into account.

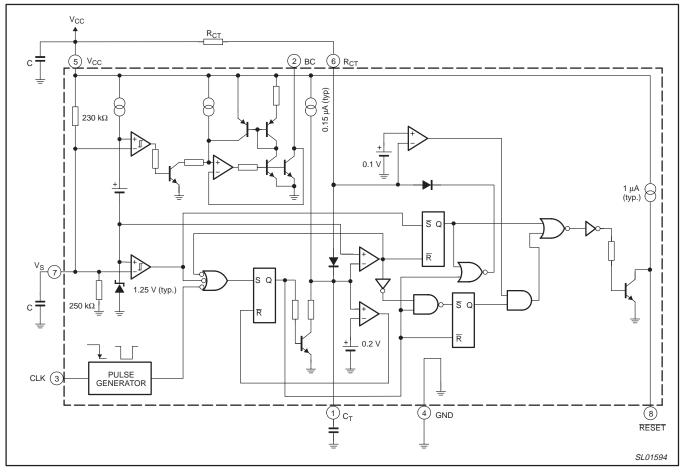


Figure 16. Functional diagram.

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Product data

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Timing diagram

The timing diagram shown in Figure 17 depicts the operation of the device. Letters indicate events on the TIME axis.

A: At start-up 'A', the V_{CC} voltage begins to rise. Also the RESET and Battery Check (BC) voltages initially rise, but then abruptly return to a LOW state. This is due to V_{CC} reaching the level of 0.8 V that activates the internal bias circuitry, asserting RESET and BC.

B: Just before 'B', the C_T voltage starts to ramp up. This is caused by, and coincident to, V_{CC} reaching the threshold level of V_{SHR}. At this level the device initiates the RESET delay time, t_{PLH}. V_{CC} continues to rise above V_{SHR}.

C: At 'C', V_{CC} rises to the threshold level of V_{SHB} , the upper voltage BC detection threshold. At this level, the BC output goes HIGH. BC output follows V_{CC} to its normal operating level.

D: At 'D', V_{CC} is above the undervoltage detect threshold and C_T has ramped up to its upper detect level. At this point, an internal ramp discharge transistor activates, discharging C_T . Reset assertion is still in effect since the delay time has not elapsed.

E: At 'E', the delay time has elapsed and the device removes the hold on the reset. RESET goes HIGH.

In a microprocessor based system these events remove the reset from the microprocessor, allowing it to function normally. The system must send clock signals to the Watchdog Timer often enough to prevent C_T from ramping up to the C_T threshold, to prevent reset signals from being generated. Each clock signal discharges C_T .

E–F: Midway between 'E' and 'F', the CLK signals cease allowing the C_T voltage to ramp up to its RESET threshold at 'F'. At this time reset signals are generated (RESET goes LOW). The device attempts to come out of reset as the C_T voltage is discharged, and finally does come out of reset when CLK signals are reestablished after two attempts of C_T.

G–I: Immediately before 'G', falling V_{CC} causes the RESET and BC outputs to sag. CLK signals are still being received, and C_T is

within normal operating range. V_{CC} continues to sag until the V_{SLB} battery check undervoltage threshold is reached. At that time (G), BC output goes LOW. V_{CC} sags still further until V_{SLR} reset undervoltage threshold is reached. At this point (H), reset is asserted and RESET goes LOW. Between 'H' and 'I', V_{CC} starts to rise, however, C_T voltage does not start to ramp up until 'I', when V_{CC} reaches the V_{SHR} upper reset threshold. Also, the RESET delay is initiated.

J–K: At 'J', the BC output goes HIGH when V_{CC} rises to V_{SHB} . Between 'J' and 'K, C_T reaches the upper threshold level again. At 'K', RESET delay time elapses and the reset is released and RESET goes HIGH.

L–M: From 'L' to 'M', the R_{CT} is shorted to ground. This disables the Watchdog timer by shorting C_T to ground. At other times R_{CT} is open or taken to V_{CC} with a resistor of 1 M Ω or greater. This configuration enables the Watchdog timer.

N: After 'N', normal CLK signals are received, but at a lower frequency than those following event 'D'. The frequency is above the minimum frequency required to keep the device from outputting reset signals.

O–P: At 'O', V_{CC} is normal, CLK signals are being received, and no reset signals are output. At event 'P', the V_{CC} starts falling, causing RESET and BC to also fall.

Q: At event 'Q' V_{CC} sags to the point where the V_{SLR} undervoltage threshold point is reached, and at that level reset signal is outputted (RESET to a LOW state).

R: At event 'R' the V_{CC} voltage has deteriorated to a level where normal internal circuit bias is no longer able to maintain a RESET, and as a result may exhibit a slight rise to something less than 0.8 V. As V_{CC} decays even further, RESET also decreases to zero.

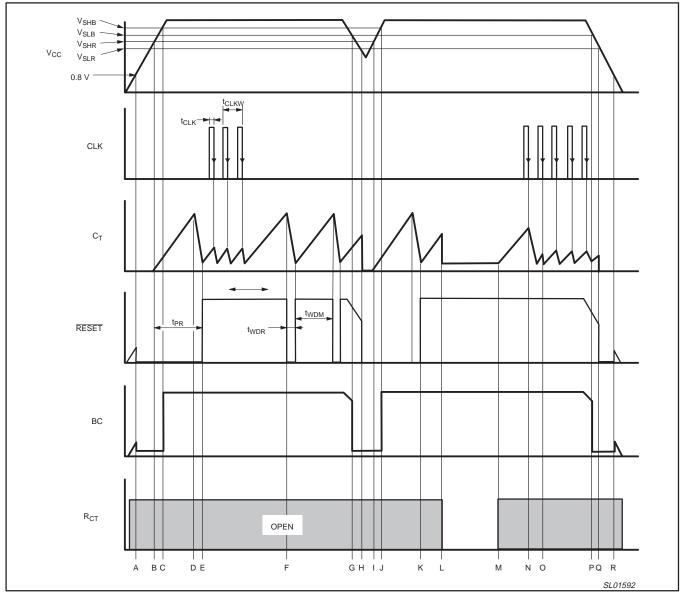


Figure 17. Timing diagram.

NE56625-20

System reset with Watchdog timer

APPLICATION INFORMATION

Detection threshold

The detection threshold voltage can be adjusted by externally influencing the internal divider reference voltage. Figures 18 and 20 show a method to raise and lower the threshold voltage. Figures 19 and 21 show the influence of the pull-down and pull-up resistors on the threshold voltage. The use of a capacitor (1000 pF or larger) from pin 7 to ground is recommended to filter out noise from being imposed on the threshold voltages.

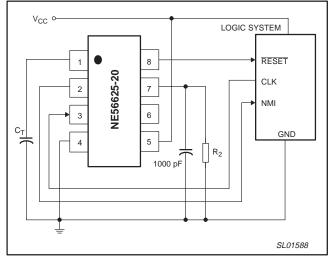
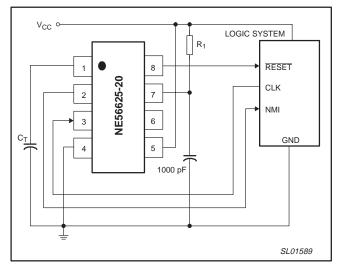


Figure 18. Circuit to raise detection threshold.





The Reset Detection Threshold can be increased by connecting an external resistor R_1 from Pin 7 to ground, as shown in Figure 18. See Figure 19 to determine the approximate value of R_1 to use. The threshold made be varied somewhat linearly from 2.4 V to 3.0 V.

The Reset Detection Threshold can be decreased by connecting an external resistor R₂ from Pin 7 to V_{CC}, as shown in Figure 20. See Figure 21 to determine the approximate value of R₂ to use. The lower thresholds may be varied in a linear fashion from 1.85 V to 1.65 V.

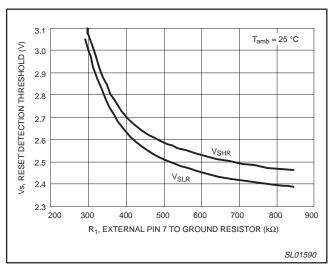


Figure 19. Reset detection threshold versus external R₁.

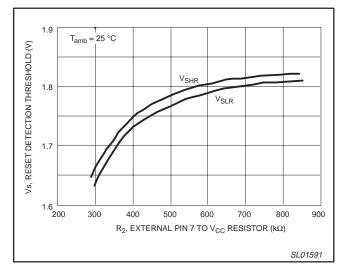


Figure 21. Reset detection threshold versus external R₂.

Product data

NE56625-20

Watchdog monitoring time

The Watchdog timer's external component values are critical to its performance.

The values of R_{CT} and C_T affect the Watchdog monitoring time (t_{WDM}), the Watchdog reset time (t_{WDR}), and power-on reset delay time (t_{PR}). See Formula 1 in the AC Electrical Characteristics and the timing diagram shown in Figure 17 for parameter definitions.

The effect of RCT on the Watch-Dog Timer Monitoring Time at room temperature for CT = $0.0022 \,\mu\text{F}$ is shown in Figure 22.

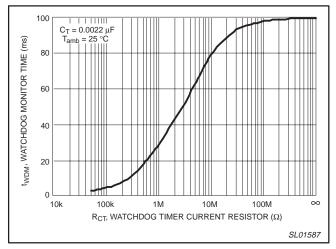


Figure 22. Watchdog monitoring vs. pull-up resistor R_{CT}.

PACKING METHOD

The NE56625-20 is packed in reels, as shown in Figure 23.

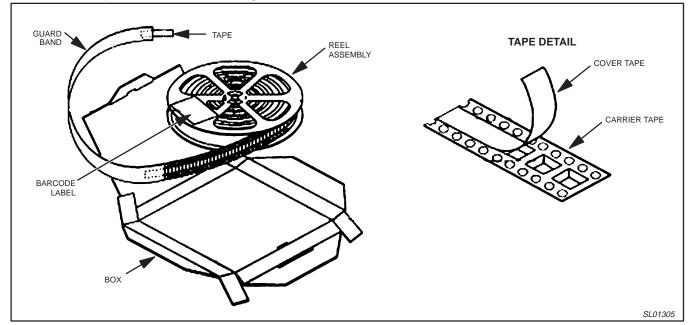
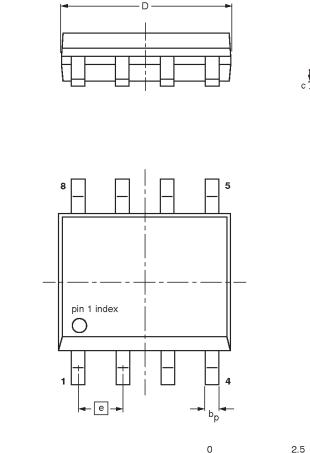
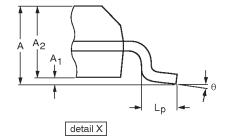


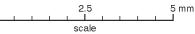
Figure 23. Tape and reel packing method.

SO8: plastic small outline package; 8 leads; body width 3.9 mm





ΗE



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	Α ₁	A ₂	b р	c	D ⁽¹⁾	E ⁽²⁾	е	H _E	Lp	θ
mm	1.73	0.25 0.10	1.45 1.25	0.51 0.33	0.25 0.19	4.95 4.80	4.0 3.8	1.27	6.2 5.8	1.27 0.38	8 ⁰
inches	0.068	0.010 0.004	0.057 0.049		0.0100 0.0075		0.16 0.15	0.050	0.244 0.228	0.050 0.015	0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFEF	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOP005	076E03	MS-012				03-10-07

SOP005

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NE56625-20

REVISION HISTORY

Rev	Date	Description
_2	20031015	Product data (9397 750 12124). ECN 853-2327 30314 of 08 September 2003. Supersedes data of 2002 Mar 25 (9397 750 09645).
		Modifications:
		• Change package version to SOP005 in Ordering information and Package outline sections.
_1	20020325	Product data (9397 750 09645). ECN 853-2327 27919 of 25 March 2002.

Data sheet status

Level	Data sheet status ^[1]	Product status ^{[2] [3]}	Definitions
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

[1] Please consult the most recently issued data sheet before initiating or completing a design.

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